

/ Descriptions

TO-263

Schottky Barrier Diode in a TO-263 Plastic Package.

/ Features

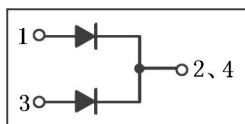
Low forward voltage drop, low power losses, High efficiency operation.

/ Applications

OR-ing

DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit**/ Pinning**

PIN1 Anode

PIN 2 4 Cathode

PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings($T_a=25$)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	45	V
Average forward rectified Current	I_F	2X15	A
Non Repetitive Peak Surge Current	I_{FSM}	250	A
Thermal Resistance Junction to Case	R_{JC}	2.8	/W
Junction and Storage Temperature Range	$T_j T_{stg}$	-40~+150	

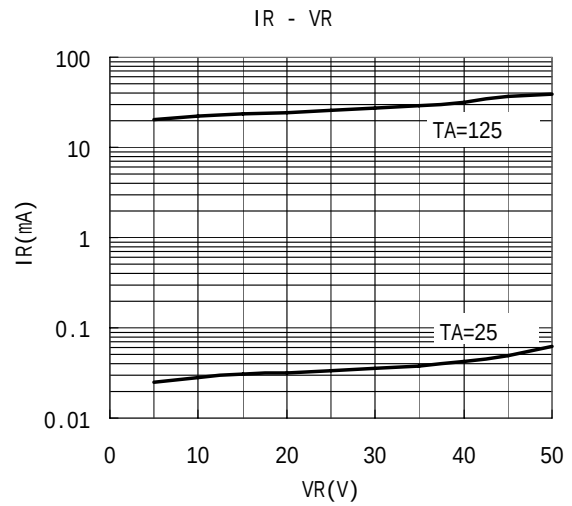
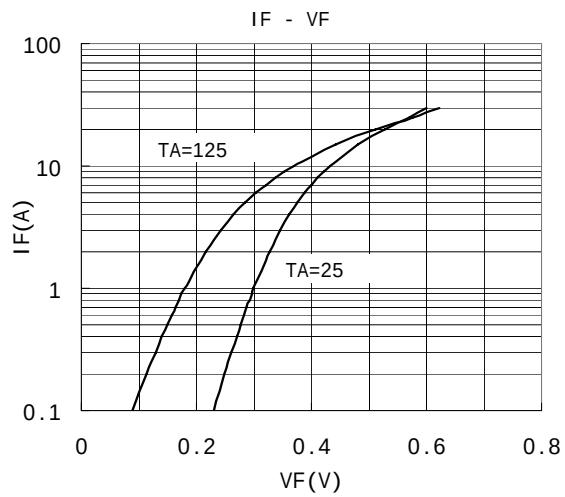
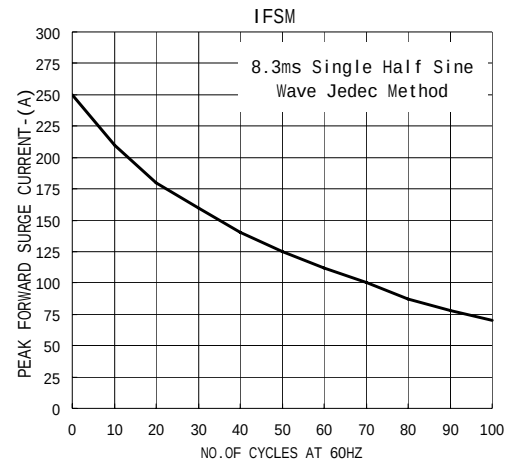
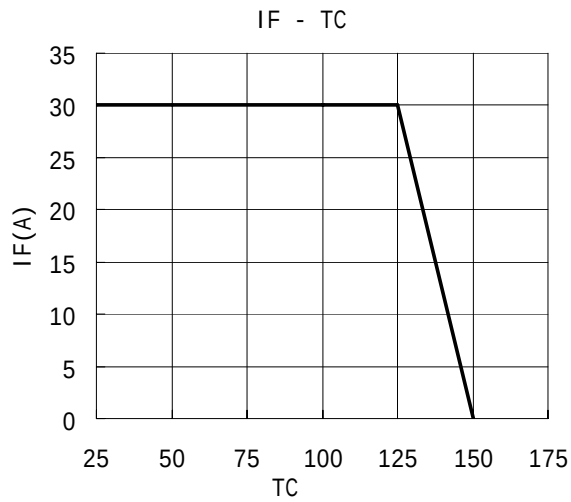
/ Electrical Characteristics($T_a=25$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA$ $T_a=25$	45			V
Forward Voltage	V_{FM}	$I_F=5.0A$ $T_a=25$		0.38	0.45	V
		$I_F=15A$ $T_a=25$		0.48	0.55	V
		$I_F=5A$ $T_a=125$		0.28	0.35	V
		$I_F=15A$ $T_a=125$		0.45	0.50	V
Instantaneous Reverse Current	I_R Note 1	$V_R=45V$ $T_a=25$			200	μA
		$V_R=45V$ $T_a=125$		40	100	mA

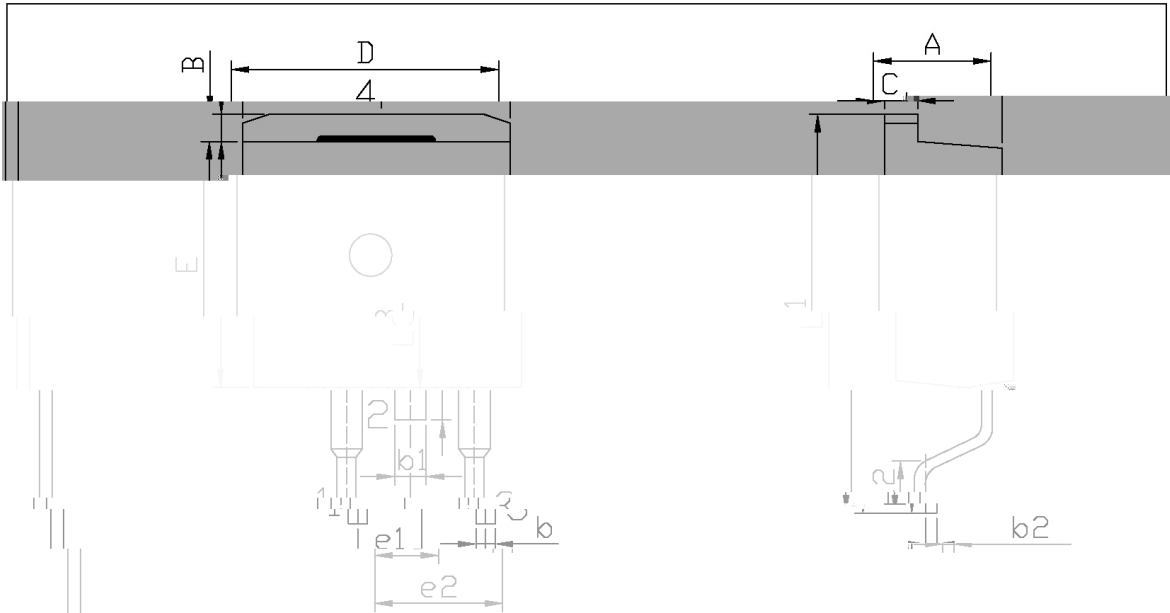
/Notes

1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip.

I Electrical Characteristic Curve



/ Package Dimensions

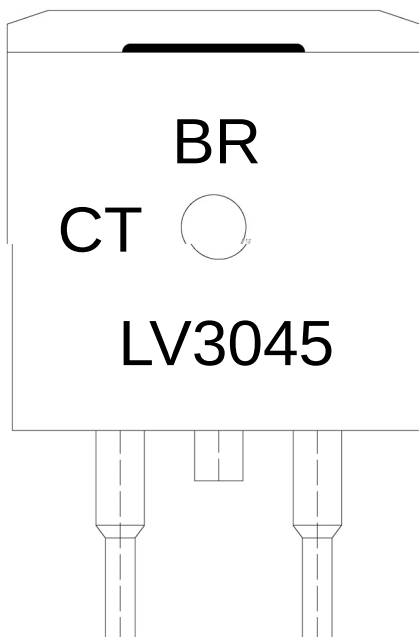


单位: mm

Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
A	4.30	4.70	E	9.00	9.50
B	1.30	1.40	e1	2.34	2.54
b	0.70	0.90	e2	4.88	5.08
b1	1.15	1.35	L1	15.00	16.00
b2	0.40	0.60	L2	2.24	2.84
C	1.20	1.40	L3	1.20	1.60
D	9.80	10.20			

TT-267

/ Marking Instructions



BR

LV3045

CT:

Note:

BR:

Company Code

LV3045

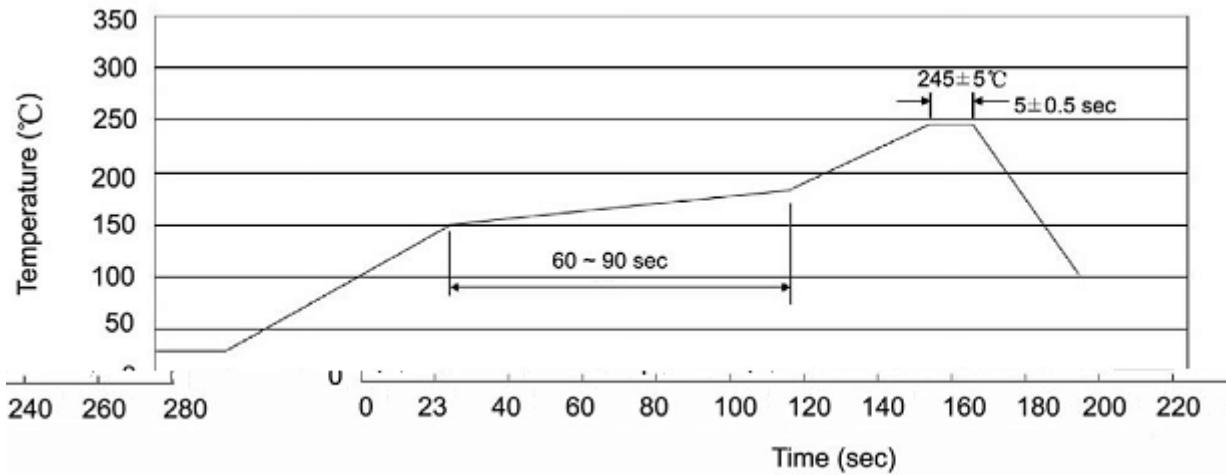
Product Type.

CT:

Internal Structure

****:

Lot No. Code, code change with Lot No.


() / Temperature Profile for IR Reflow Soldering(Pb-Free)


Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.
/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices